

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.01	2.3	0.02
		Silicon (Si)	7440-21-3	0.53	97.7	0.98
		Subtotal		0.54	100	1
Clip Frame	Copper alloy	Phosphorous (P)	7723-14-0	0	0.04	0
	Copper alloy	Iron (Fe)	7439-89-6	0	0.1	0.01
	Copper alloy	Copper (Cu)	7440-50-8	3.34	99.86	6.19
		Subtotal		3.34	100	6.2
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06	5.0	0.11
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.05
	Lead alloy	Lead (Pb)	7439-92-1	1.07	92.5	1.99
		Subtotal		1.16	100	2.15
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.13	100.0	2.1
		Subtotal		1.13	100	2.1
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.53	8.0	8.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.99	8.8	9.24
	Filler	Silica fused	60676-86-0	47.02	83.0	87.15
	Carbon Black	Carbon black	1333-86-4	0.11	0.2	0.21
		Subtotal		56.65	100	105
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.04	0.03
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.07
	Copper alloy	Copper (Cu)	7440-50-8	37.12	99.86	68.8
		Subtotal		37.17	100	68.9
		Total		99.99	100	185.35

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